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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/981,402	10/17/2001	Yoshihiro Satoh	N32040200W	6789
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Darryl G. Walker WALKER & SAKO, LLP Suite 235			EXAMINER	
			RICHARDS, N DREW	
300 South First Street San Jose, CA 95113			ART UNIT	PAPER NUMBER
-			2815	-
			DATE MAILED: 05/23/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

-		Application No.	Applicant(s)
ĺ	•	09/981,402	
	Office Action Summary	Examiner	SATOH, YOSHIHIRO Art Unit
	•	N. Drew Richards	2815
	The MAILING DATE of this communication ap		
THE - Exte after - If the - If NC - Failu - Any I	ORTENED STATUTORY PERIOD FOR REPL MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. It period for reply specified above is less than thirty (30) days, a replayer of the provided period for reply will, by statutive to reply within the set or extended period for reply will, by statutive reply received by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, ma ly within the statutory minimum of will apply and will expire SIX (6) I	thirty (30) days will be considered timely. MONTHS from the mailing date of this communication.
1)	Responsive to communication(s) filed on <u>02</u>	May 2003	
2a)⊠		nis action is non-final.	
3)□	/_		
,	Since this application is in condition for allow closed in accordance with the practice under con of Claims	Ex parte Quayle, 1935	C.D. 11, 453 O.G. 213.
4)⊠	Claim(s) 1.2 and 7-24 is/are pending in the ap	oplication.	
	4a) Of the above claim(s) <u>7-20</u> is/are withdraw	n from consideration.	
5)	Claim(s) is/are allowed.		
6)⊠	Claim(s) 1,2 and 21-24 is/are rejected.		
7)	Claim(s) is/are objected to.		
	Claim(s) are subject to restriction and/o	or election requirement.	
	on Papers		
	The specification is objected to by the Examine		
10)[The drawing(s) filed on is/are: a)□ acce		
44)[7]	Applicant may not request that any objection to the		
11)[X]	The proposed drawing correction filed on 16 De		pproved b) disapproved by the Examine
12\□ 7	If approved, corrected drawings are required in re		
	The oath or declaration is objected to by the Ex	aminer.	
	nder 35 U.S.C. §§ 119 and 120		
_	Acknowledgment is made of a claim for foreign	n priority under 35 U.S.(C. § 119(a)-(d) or (f).
	✓ All b) Some * c) None of:1. Certified copies of the priority document		
			A 41
	 Copies of the certified copies of the prio application from the International Bu ee the attached detailed Office action for a list 	reau (PCT Rule 17.2(a)).
_	cknowledgment is made of a claim for domesti		
a)	☐ The translation of the foreign language procknowledgment is made of a claim for domest	visional application has	been received.
Attachment		, , , , , , , , , , , , , , , , , , , ,	
2) D Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449) Paper No(s) _	5) Notice	w Summary (PTO-413) Paper No(s) of Informal Patent Application (PTO-152)
S. Patent and Tra PTO-326 (Rev	A 4 A 41	tion Summary	Part of Paper No. 12

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DETAILED ACTION

Drawings

1. The proposed drawing correction and/or the proposed substitute sheets of drawings, filed on 12/16/02 have been approved. A proper drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application. The correction to the drawings will not be held in abeyance.

DETAILED ACTION

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.
- 3. Claims 1, 2, and 21-24 are rejected under 35 U.S.C. 102(a) as being anticipated by Applicant's admitted prior art.

Applicant's admitted prior art, hereafter referred to as "APA", discloses in figures 16-21 a semiconductor device comprising a contact 30 which penetrates an interlayer insulating film 26 and is electrically connected with a diffusion layer (not shown) in the silicon substrate, a gate electrode 16,18 which is formed on the silicon substrate and contains a nitride film 20,24 at upper and side portions, and a silicon nitride film 20,24 for preventing carbon diffusion, which is formed on the silicon substrate while traversing a region except a portion for providing the electrical connection between the contact and

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the diffusion layer, and is formed on the nitride film at the upper and side portions of the gate electrode. Films 20 and 24 each considered two separate nitride layers laminated on one another where the first layer (the lower portion of 20 and the inside portion of 24) are the nitride film on the gate electrode while the second layer (the upper portion of 20 and the outside portion of 24) are the silicon nitride film for preventing carbon diffusion.

With regard to claim 2, the insulating film is disclosed on page 3 lines 8 and 9 as including tantalum oxide (Ta_2O_5) and the device is disclosed as being a dynamic random access memory having a memory cell capacitor film including the tantalum oxide.

With regard to claim 21, APA discloses a contact 30 which penetrates a first interlayer insulating film 26 and is electrically connected with a diffusion layer (not shown) in the silicon substrate, a capacitor contact 46 that is interposed between a lower electrode of the memory cell capacitor (not shown) and the contact 30 while penetrating a second interlayer insulating film 26 and a third interlayer insulating film 26, a conductor 33,34 which is formed on the second interlayer insulating film 26 and contains a nitride film 36,40 at upper and side portions, and a silicon nitride film 36,40 for preventing carbon diffusion formed on the third interlayer insulating film 32 while traversing a region except a connection portion between the lower electrode and the capacitor contact, and is formed above the nitride film at the upper portion of the conductor. Film 26 is considered a second interlayer insulator (bottom portion) and a third interlayer insulator (top portion) of the same material formed one on top of the other. Films 36 and 40 are each considered two separate nitride layers laminated on

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one another where the first layer (the lower portion of 36 and the inside portion of 40) are the nitride film on the conductor while the second layer (the upper portion of 36 and the outside portion of 40) are the silicon nitride film for preventing carbon diffusion.

With regard to claim 22, the insulating film is disclosed on page 3 lines 8 and 9 as including tantalum oxide (Ta_2O_5) and the device is disclosed as being a dynamic random access memory having a memory cell capacitor film including the tantalum oxide.

With regard to claim 23, APA discloses a contact 30 that is electrically connected with a diffusion layer (not shown) formed in the silicon substrate while penetrating a first interlayer insulating film 26, the contact is electrically connected to a capacitor contact 46 that is interposed between a lower electrode of a memory cell capacitor (not shown) and the contact 30 while penetrating a second interlayer insulating film 32 and a third interlayer insulating film 42 for providing an electrical connection between the lower electrode and the contact, a conductor 33,34 which is formed on the second interlayer insulating film 32 and contains a nitride film 36,40 at upper and side portions, a silicon nitride film 36,40 for preventing carbon diffusion formed between the second and third interlayer insulating films while traversing a region except a connection portion between the lower electrode and the capacitor contact, and is formed on the nitride film at the upper and side portions of the conductor. Films 36 and 40 each considered two separate nitride layers laminated on one another where the first layer (the lower portion of 36 and the inside portion of 40) are the nitride film on the conductor while the second

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layer (the upper portion of 36 and the outside portion of 40) are the silicon nitride film for preventing carbon diffusion.

With regard to claim 24, the insulating film is disclosed on page 3 lines 8 and 9 as including tantalum oxide (Ta₂O₅) and the device is disclosed as being a dynamic random access memory having a memory cell capacitor film including the tantalum oxide.

Response to Arguments

4. Applicant's arguments filed 5/2/03 have been fully considered but they are not persuasive.

Applicant argues that the background art does not show a silicon nitride film formed on a nitride film at the upper and side portions of the gate electrode as claimed in claim 1. This is not persuasive as in the rejection above it is explained that silicon nitride films 20 and 24 are considered two films laminated on one another. The inner portion of 24 (contacting the gate electrode) and the lower portion of 20 (contacting the gate electrode) are considered the first nitride film formed at upper and side portions of the gate electrode. The outer portion of 24 (contacting insulator 26) and the upper portion of 20 (contacting insulator 26) are considered the silicon nitride film for preventing carbon diffusion. (There is no structural difference between the single layers 20 and 24 being considered two layers and two layers of the same material formed one on the other.

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Applicant also argues that the nitride films 20 and 24 do not traverse a region except a portion for providing electrical communication between the contact and the diffusion layer. This is not persuasive as layers 20 and 24 do traverse such a region. Layers 20 and 24 as shown in figure 16a traverse a region from the left side of the leftmost gate electrode to the right side of the rightmost gate electrode except for a portion for providing electrical communication between the contact and the diffusion layer. The claim language does not require the nitride film to traverse all regions except the portion for electrical communication, the claim language only require the nitride film to traverse a (single) region. Thus, nitride films 20 and 24 meet this limitation.

The argument with regard to claim 21 that the capacitor contact of the rejection does not penetrate the second and third interlayer insulator is mute in view of the new rejection above.

Applicant also argues with regard to claims 21-24 that the background art does not teach the silicon nitride film for preventing carbon diffusion formed above a nitride film at the upper portion of the conductor. This is not persuasive as in the rejection above it is explained that silicon nitride films 36 and 40 are considered two films laminated on one another. The inner portion of 40 (contacting the conductor) and the lower portion of 36 (contacting the conductor) are considered the nitride film at upper and side portions of the conductor. The outer portion of 40 (contacting insulator 42) and the upper portion of 36 (contacting insulator 42) are considered the silicon nitride film for preventing carbon diffusion. There is no structural difference between the single layers

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40 and 36 being considered two layers and two layers of the same material formed one on the other.

Applicant also argues that nitride films 36 and 40 do not traverse a region except a portion for providing electrical communication between the contact and the diffusion layer. This is not persuasive as layers 36 and 40 do traverse such a region. Layers 36 and 40 as shown in figure 17 traverse a region from the left side of the leftmost conductor 33,34 to the right side of the rightmost conductor 33,34 except for a portion for providing electrical communication between the contact and the diffusion layer. The claim language does not require the nitride film to traverse all regions except the portion for electrical communication, the claim language only require the nitride film to traverse a (single) region. Thus, nitride films 36 and 40 meet this limitation.

Conclusion

5. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any

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extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to N. Drew Richards whose telephone number is (703) 306-5946. The examiner can normally be reached on M-F 8:00-5:30; Every other Friday off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie Lee can be reached on (703) 308-1690. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

NDR

May 20, 2003

EDDIE LEE

SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 2800